PCN Number:	20170927001-001	**PCN Date:**	Oct. 3, 2017
Title:	Qualify New Assembly Material set for Selected Device(s)		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Apr 01, 2018	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material set for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Material	Current	Proposed
Mount compound	4042500, 4208458	4211470
Mold compound	4205694	4209640

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

None.

Product Affected:

ISO721MMDREP	ISO7241AMDWREP	V62/10606-01XE
ISO721MMDREPG4	V62/08627-01XE	

Qualification Plan

BCB site change from Amkor K4 to TIEM as well as BOM change to latest approved ISO BOM

(Qualification Target date: Apr 01, 2018)

Product Attributes

Attributes	Qual Device: AMC1203BDUB	Qual Device: ISO7221AQDRQ1	Qual Device: ISO7221CD	Qual Device: ISO7221CHD	Qual Device: AMC1203BDW	Qual Device: ISO3082DW	Qual Device: ISO35TDW	Qual Device: ISO7241CQDWRQ1
Assembly Site	HNT	TAI	TAI	TAI	TAI	TAI	TAI	TAI
Package Family	SOP	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DFAB, TSMC	DFAB	DFAB	DFAB	DFAB, TSMC	DFAB	DFAB	DFAB
Wafer Fab Process	0.5UM, LBC4	LBC4	LBC4	LBC4	0.5UM, LBC4	LBC3S, LBC4	LBC4, lbc3s	LBC4

- QBS: Qual By Similarity
- Qual Devices ISO7221CHD and ISO7221CD are qualified at LEVEL1-260C
- Qual Devices ISO3082DW and ISO35TDW are qualified at LEVEL2-260C
- Qual Devices ISO7241CQDWRQ1, AMC1203BDUB, AMC1203BDW, and ISO7221AQDRQ1 are qualified at LEVEL3-260C
- The following Devices contain multiple dies: ISO35TDW, ISO7221CHD, ISO7221CD, ISO7241CQDWRQ1, AMC1203BDUB, ISO7221AQDRQ1, AMC1203BDW, ISO3082DW

Qualification Plan

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ..AMC1203BDUB	Qual Device: .ISO7221AQDRQ1	Qual Device: .ISO7221CD	Qual Device: .ISO7221CHD
AC	Autoclave 121C	96 Hours	3/77/TBD	3/77/TBD	3/77/TBD	1/77/TBD
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	TBD	TBD	TBD
HAST	**Biased HAST 130C/85%RH	96 Hours	3/77/TBD	3/77/TBD	3/77/TBD	-
HTOL	Life Test, 140C	480 Hours	-	3/77/TBD	-	-
HTSL	High Temp. Storage Life, 175C	500 Hours	-	1/45/TBD	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/77/TBD	-	3/77/TBD	-
TC	Temperature Cycle, -65/150C	Cycles	3/77/TBD	3/77/TBD	3/77/TBD	-

Type	Test Name / Condition	Duration	Qual Device: ..AMC1203BDUB	Qual Device: .ISO7221AQDRQ1	Qual Device: .ISO7221CD	Qual Device: .ISO7221CHD
WBP	Bond Pull	76 Wires, 3 units min	3/76/TBD	3/76/TBD	3/76/TBD	3/76/TBD
WBS	Ball Bond Shear	Wires	3/76/TBD	3/76/TBD	3/76/TBD	3/76/TBD

Type	Test Name / Condition	Duration	Qual Device: AMC1203BDW	Qual Device: ISO3082DW	Qual Device: ISO35TDW	Qual Device: ISO7241CQDWRQ1
AC	Autoclave 121C	96 Hours	1/77/TBD	1/77/TBD	1/77/TBD	3/77/TBD
ED	Electrical Characterization	Per Datasheet Parameters	TBD	TBD	TBD	-
HAST	**Biased HAST 130C/85%RH	96 Hours	-	-	-	3/77/TBD
HTOL	Life Test, 140C	480 Hours	-	-	-	3/77/TBD
HTSL	High Temp. Storage Life, 175C	500 Hours	-	-	-	1/45/TBD
HTSL	High Temp. Storage Bake, 170C	420 Hours	1/77/TBD	1/77/TBD	1/77/TBD	-
TC	Temperature Cycle, -65/150C	Cycles	1/77/TBD	1/77/TBD	1/77/TBD	3/77/TBD
WBP	Bond Pull	76 Wires, 3 units min	1/76/TBD	1/76/TBD	1/76/TBD	3/76/TBD
WBS	Ball Bond Shear	Wires	1/76/TBD	1/76/TBD	1/76/TBD	3/76/TBD

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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